



#### **Product Summary**

BV <sub>DSS</sub>	Rds(on) Max	I <sub>D</sub> Max T <sub>A</sub> = +25°C
001/	46mΩ @ V <sub>GS</sub> = 4.5V	3.1A
20V	53mΩ @ V <sub>GS</sub> = 2.5V	2.8A

# N-CHANNEL ENHANCEMENT MODE MOSFET

#### **Features and Benefits**

- Low On-Resistance
- Low Input Capacitance
- Fast Switching Speed
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- The DMN2055UWQ is suitable for automotive applications requiring specific change control; this part is AEC-Q101 qualified, PPAP capable, and manufactured in IATF 16949 certified facilities.

https://www.diodes.com/guality/product-definitions/

## **Description and Applications**

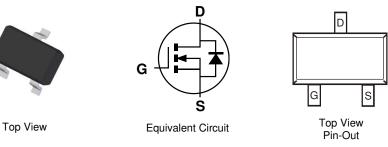
This MOSFET is designed to minimize the on-state resistance  $(R_{DS(ON)})$  yet maintain superior switching performance, making it ideal for high efficiency power management applications.

- General Purpose Interfacing Switch
- Power Management Functions
- DC-DC Converters
- Analog Switch

SOT323

## **Mechanical Data**

- Case: SOT323
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections Indicator: See Diagram
- Terminals: Finish Matte Tin Annealed over Copper Leadframe. Solderable per MIL-STD-202, Method 208 (C3)
- Weight: 0.027 grams (Approximate)



#### Ordering Information (Note 4)

Part Number	Case	Packaging
DMN2055UWQ-7	SOT323	3,000/Tape & Reel
DMN2055UWQ-13	SOT323	10,000/Tape & Reel

Notes: 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant. 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.

3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.

4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.

## Marking Information

		]		
I	BA5		ΥM	

 $\begin{array}{l} \mathsf{BA5}=\mathsf{Product}\;\mathsf{Type}\;\mathsf{Marking}\;\mathsf{Code}\\ \mathsf{YM}\;\mathsf{or}\;\overline{\mathsf{Y}}\mathsf{M}=\mathsf{Date}\;\mathsf{Code}\;\mathsf{Marking}\\ \mathsf{Y}\;\mathsf{or}\;\overline{\mathsf{Y}}=\mathsf{Year}\;(\mathsf{ex:}\;\mathsf{H}=2020) \end{array}$ 

M = Month (ex: 9 = September)

#### Date Code Key Year 2019 2020 2021 2022 2023 2024 2025 2026 2027 2028 2029 2030 Code G Η Κ Μ Ν Ρ R S J 0 May Mar Oct Dec Month Jan Feb Apr Jun Jul Aug Sep Nov Code 2 3 9 0 D 1 5 6 7 8 Ν 4



# Maximum Ratings (@TA = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit		
Drain-Source Voltage	VDSS	20	V		
Gate-Source Voltage	V <sub>GSS</sub>	±8	V		
Continuous Drain Current (Note 6) $V_{GS}$ = 4.5V	Steady State	TA = +25°C	- I <sub>D</sub>	3.1	A
		TA = +70°C		2.4	
Pulsed Drain Current (10µs Pulse, Duty Cycle = 1%)			Ідм	22	А
Maximum Body Diode Forward Current (Note 5)			ls	0.8	А

## Thermal Characteristics (@TA = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Unit
Total Power Dissipation (Note 5)		PD	0.52	W
Thermal Resistance, Junction to Ambient (Note 5)	Steady State	Reja	241	°C/W
Total Power Dissipation (Note 6)	·	PD	0.65	W
Thermal Resistance, Junction to Ambient (Note 6)	Steady State	R <sub>0JA</sub>	191	°C/W
Operating and Storage Temperature Range		TJ, TSTG	-55 to +150	°C

## Electrical Characteristics (@TA = +25°C, unless otherwise specified.)

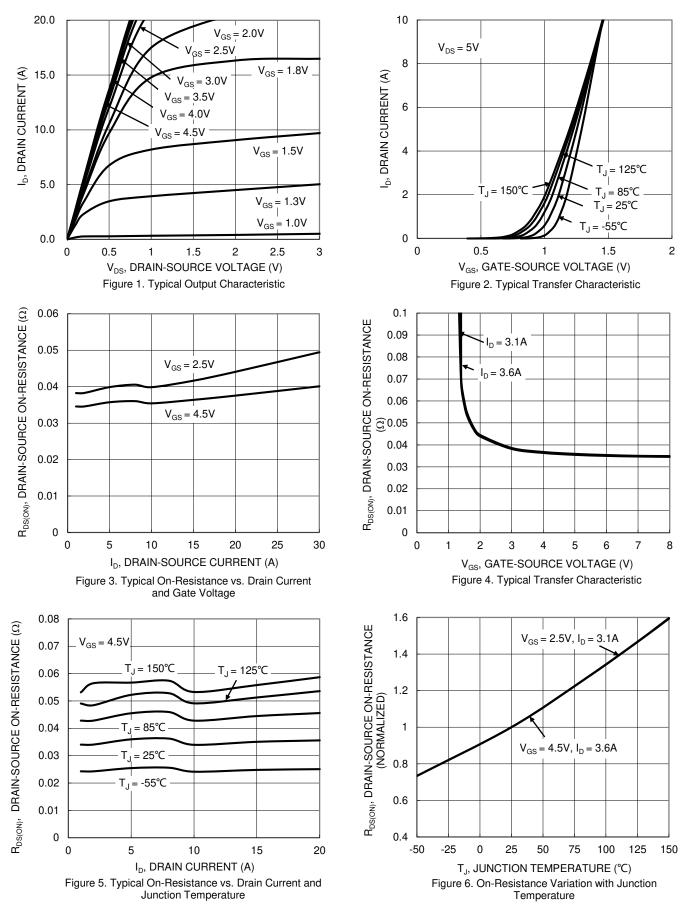
Characteristic	Symbol	Min	T <sub>1</sub> m	Мах	Unit	Test Condition	
OFF CHARACTERISTICS (Note 7)		IVIITI	Тур	wax	Unit	Test Condition	
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	20	_	_	V	Vgs = 0V, Ip = 250µA	
Zero Gate Voltage Drain Current @T <sub>C</sub> = +25°C	IDSS	_	_	1.0	μA	$V_{DS} = 20V, V_{GS} = 0V$	
Gate-Source Leakage	lgss	—	—	±100	nA	$V_{GS} = \pm 8V, V_{DS} = 0V$	
ON CHARACTERISTICS (Note 7)							
Gate Threshold Voltage	Vgs(th)	0.4	—	1.0	V	$V_{DS} = V_{GS}$ , $I_D = 250 \mu A$	
Chatia Duaia Cauraa On Daaiatanaa		_	35	46		V <sub>GS</sub> = 4.5V, I <sub>D</sub> = 3.6A	
Static Drain-Source On-Resistance	RDS(ON)		39	53	mΩ	V <sub>GS</sub> = 2.5V, I <sub>D</sub> = 3.1A	
Diode Forward Voltage	Vsd		0.7	1	V	$V_{GS} = 0V, I_S = 1A$	
DYNAMIC CHARACTERISTICS (Note 8)							
Input Capacitance	Ciss		400		pF		
Output Capacitance	Coss	—	55	—	pF	VDS = 10V, VGS = 0V, f = 1.0MHz	
Reverse Transfer Capacitance	Crss	—	37	—	pF		
Gate Resistance	Rg	_	3.7	_	Ω	$V_{DS} = 0V, V_{GS} = 0V, f = 1MHz$	
Total Gate Charge	Qg	_	4.3	_	nC		
Gate-Source Charge	Qgs	_	0.3	_	nC	$V_{GS} = 4.5V, V_{DS} = 10V,$	
Gate-Drain Charge	Q <sub>gd</sub>	_	4.8	_	nC	ID = 6A	
Turn-On Delay Time	t <sub>D(ON)</sub>	_	2.8	_	ns		
Turn-On Rise Time	tR	_	2.7	—	ns	$V_{DD} = 10V, V_{GS} = 5V,$	
Turn-Off Delay Time	td(OFF)	_	15.4	—	ns	$R_L=1.7\Omega,R_g=6\Omega$	
Turn-Off Fall Time	tF	_	4.4	—	ns		

Notes:

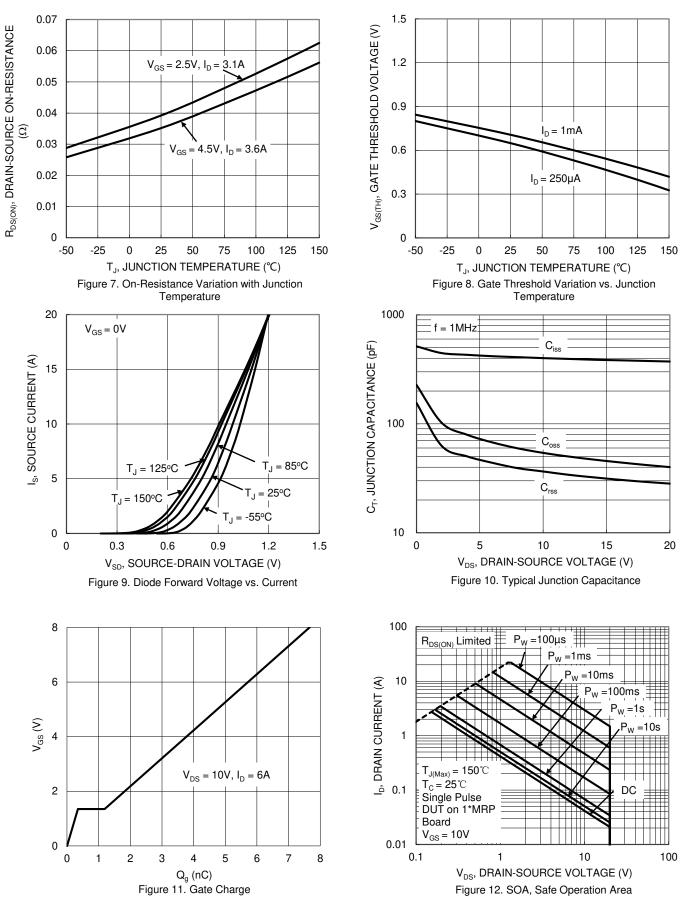
5. Device mounted on FR-4 substrate PC board, with minimum recommended pad layout.
6. Device mounted on FR-4 substrate PC board, 2oz copper, with thermal bias to bottom layer 1inch square copper plate.
7. Short duration pulse test used to minimize self-heating effect.
8. Guaranteed by design. Not subject to product testing.



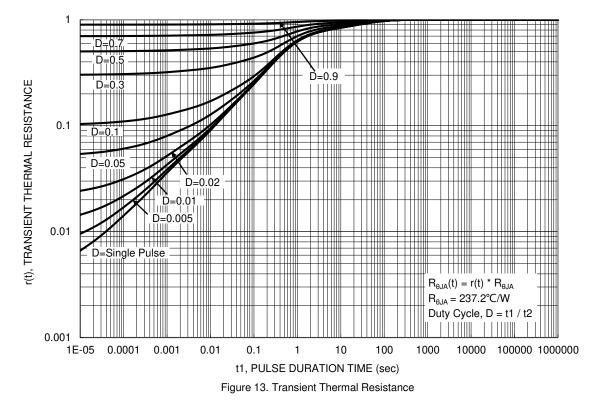
#### DMN2055UWQ









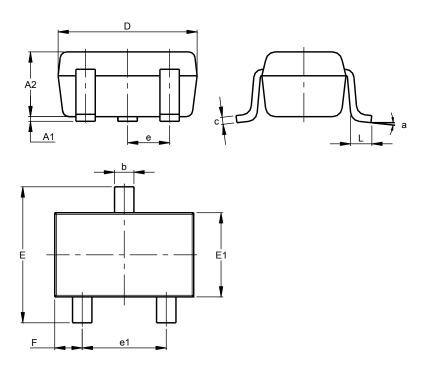




# Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

#### SOT323

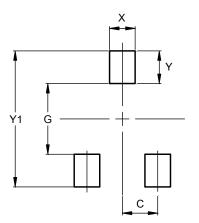


SOT323						
Dim	Min	Max	Тур			
A1	0.00	0.10	0.05			
A2	0.90	1.00	0.95			
b	0.25	0.40	0.30			
С	0.10	0.18	0.11			
D	1.80	2.20	2.15			
Е	2.00	2.20	2.10			
E1	1.15	1.35	1.30			
е	0.650 BSC					
e1	1.20	1.40	1.30			
F	0.375	0.475	0.425			
L	0.25	0.40	0.30			
а	0°	8°				
All Dimensions in mm						

## **Suggested Pad Layout**

Please see http://www.diodes.com/package-outlines.html for the latest version.

#### SOT323



Dimensions	Value (in mm)		
С	0.650		
G	1.300		
Х	0.470		
Y	0.600		
Y1	2.500		



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